

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	dipersal and coating and pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 10:09
L2	49	dispersal and coating and pcb	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 10:19
L3	7	pcb and dielectric near substrate and prepreg and thermosetting near resin and dispers\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 10:21
L4	47	("20020150673" "20020170827" "20020172019" "20020190378" "20030022103" "20040256731" "3953566" "3962653" "4187390" "4482516" "4579772" "4642160" "4675789" "4713137" "4783345" "4864722" "5129142" "5229550" "5246817" "5368921" "5376453" "5418689" "5483101" "5565267" "5648171" "5652055" "5670262" "5677045" "5685070" "5726863" "5814405" "5822856" "5981880" "6018196" "6042685" "6119338" "6143401" "6207595" "6212769" "6248959" "6291779" "6323436" "6378201" "6405431" "6506979" "6541589" "6586687").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/12 10:26
L5	1	"6753843".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/12 10:26
L6	1	"6753483".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/12 10:56
L7	7	("5346750" "5484647" "5807626" "5888627" "6326694").PN. OR ("6753483").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/12 10:28
L8	0	Ueda near Yoji.inv. and disperse near pcb	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 10:57

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L9	7	Ueda near Yoji .inv. and disper\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 10:59
L10	2	dispersal and pcb and (174/262-266; 174/254 ; 174/258 ; 174/260 ; 174/261 ; 174/267 ; 361/792-795 ; 361/750 ; 428/209-210 ; 428/901 ; 29/841-852).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:03
L11	92	dispers\$3 and pcb and (174/262-266; 174/254 ; 174/258 ; 174/260 ; 174/261 ; 174/267 ; 361/792-795 ; 361/750 ; 428/209-210 ; 428/901 ; 29/841-852).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:00
L12	0	dispers\$3 near dielectric and pcb and (174/262-266; 174/254 ; 174/258 ; 174/260 ; 174/261 ; 174/267 ; 361/792-795 ; 361/750 ; 428/209-210 ; 428/901 ; 29/841-852).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:01
L13	0	dispers\$3 near substrate and pcb and (174/262-266; 174/254 ; 174/258 ; 174/260 ; 174/261 ; 174/267 ; 361/792-795 ; 361/750 ; 428/209-210 ; 428/901 ; 29/841-852).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:01
L14	0	dispers\$3 near substrate and pcb and (174/262-266; 174/254 ; 174/258 ; 174/260 ; 174/261 ; 174/267 ; 361/792-795 ; 361/750 ; 428/209-210 ; 428/901 ; 29/841-852).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:01
L15	37	dispers\$3 near substrate and pcb	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:01
L16	4	dispersal and pcb and (29/831; 29/832 ; 29/841 ; 29/854 ; 29/855 ; 29/840 ; 174/252 ; 257/706 ; 257/707 ; 257/712 ; 257/713 ; 361/719 ; 361/720 ; 428/209 ; 428/469 ; 428/420 ; 428/901).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:04

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L17	85	dispers\$3 and pcb and (29/831; 29/832 ; 29/841 ; 29/854 ; 29/855 ; 29/840 ; 174/252 ; 257/706 ; 257/707 ; 257/712 ; 257/713 ; 361/719 ; 361/720 ; 428/209 ; 428/469 ; 428/420 ; 428/901).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:05
L18	20	dispers\$3 and thermosetting near resin and pcb and (29/831; 29/832 ; 29/841 ; 29/854 ; 29/855 ; 29/840 ; 174/252 ; 257/706 ; 257/707 ; 257/712 ; 257/713 ; 361/719 ; 361/720 ; 428/209 ; 428/469 ; 428/420 ; 428/901).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:08
L19	18	dispers\$3 and thermosetting near resin and pcb and (428/196, 156/235 , 156/246 , 156/249 , 156/307.7 , 156/312 , 156/330 , 174/259 , 29/846 , 428/332 , 428/40.4 , 428/415 , 428/416 , 428/417 , 428/418 , 428/901).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 11:08